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TITLE : PREPARING POWDER COATING MATERIAL FOR USE IN CHEMICAL PLATING

ABSTRACT : PURPOSE: To provide a title powder coating material suitable for use in production of metal-cored printed circuit board, by a method wherein specifically proportioned thermosetting resin, rubber, and inorganic filler are blended, and the mixture and a specific amount of a thermosetting resin is blended and crushed into fine particles.

CONSTITUTION: A composition consists of (A) 3~50wt% of a thermosetting resin with m.p. less than 150°C, such as epoxy resin or acrylic resin, (B) 5~60wt% of an inorganic filler, such as CaCO₃ or TiO₂, and (C) a rubber having, in molecule, conjugated double bonds and polar groups in amounts of less than 80wt%, but which amount should exceed double the amount in the final composition. This composition is blended at a temperature below m.p. of (A). To this blend, a thermosetting resin is added so that the rubber component will become 1~30pts.wt. per 100pts.wt. of the thermosetting resin. The mixture is blended, and is crushed to give 300μ or less diameter fine particles. The process provides a chemical-plating-use thermosetting resin powder coating material capable of giving viscosity of less than 10⁵cps in at least one stage of heat curing.

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